

#### IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

n re application of: Nikhil Vishwanath Kelkar

Attorney Docket No.: NSC1P300/P05882

Application No.: 10/824,903

Examiner: Shankle, A.

Filed: April 14, 2004

Group: 2891

Title: WAFER LEVEL PACKAGE DESIGN

Confirmation No: 7593

THAT FACILITATES TRIMMING AND

**TESTING** 

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as first-class mail on July 12, 2006 in an envelope addressed to the Commissioner for Patents, P.O. Box 1450

Alexandria, VA 22313-145

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INFORMATION DISCLOSURE STATEMENT BEFORE FINAL ACTION OR NOTICE OF ALLOWANCE (37 CFR §§ 1.56 AND 1.97(c))

Mail Stop Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

The references listed in the attached PTO Form 1449, a copy of which is attached, may be material to examination of the above-identified patent application. Applicants submit this reference in compliance with their duty of disclosure pursuant to 37 CFR §§1.56 and 1.97. The Examiner is requested to make this citation of official record in this application.

This Information Disclosure Statement is not to be construed as a representation that a search has been made, that additional information material to the examination of this application does not exist, or that this reference indeed constitutes prior art.

This Information Disclosure Statement is being filed after the mailing date of the first Office Action on the merits, or after three months of the filing date of this application, whichever event occurred last, but it is believed before the mailing date of either: (i) a final action under §1.113 or (ii) a notice of allowance under §1.311, whichever occurs first.

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Accompanying this Information Disclosure Statement is			
	a statement as specified in 37 CFR 1.97(e); or		
	the fee set forth in 37 CFR 1.17(p).		

If fees are due, enclosed is our Check No. 30646 for \$180.00 in payment of the Information Disclosure Statement Fee. If it is determined that any additional fees are due, the Commissioner is hereby authorized to charge such fees to Deposit Account 500388 (Order No. NSC1P300).

Respectfully submitted,
BEYER WEAVER & THOMAS, LLP

Steve D Beyer

Registration No. 31, 234

P.O. Box 70250 Oakland, CA 94612-0250 Form 1449 (Modified)

Information Disclosure
Statement By Applicant

Kelkar
Filing Date

Atty Docket No. Application No.:
NSC1P300/P05882

Applicant:
Kelkar
Filing Date

Group

(Use Several Sheets if Necessary)

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Information Disclosure Statement By Applicant	Applicant: Kelkar	Ź
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